



# F81485

# **5V Low Power RS-485 Interface Transceiver**

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Version: V0.11P





#### F81485 Datasheet Revision History

Version	Date	Page	Revision History
V0.10P	2011/12	-	Preliminary
V0.12P	2012/01	-	Made Clarification and Correction Update Top Marking Specification Update Differential Input Threshold Spec.

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#### LIFE SUPPORT APPLICATIONS

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### 1 General Description

The F81485 is a CMOS design, features with single 5 V power supply, and low power differential bus/line transceiver suitable for the multipoint data transmission EIA standard RS485 and RS422 applications. The extended common-mode range is –7 V to +12 V. Both the driver and the receiver can be enabled independently. The driver and receiver feature three-state outputs, with the driver outputs maintaining high impedance over the entire common-mode range. Excessive power dissipation caused by the bus contention or faults is prevented by a thermal shutdown circuit which forces the driver outputs into a high impedance state. The receiver contains a fail-safe feature that results in a logic high output state if the inputs are unconnected (floating). Up to 32 transceivers can be connected simultaneously on a bus, but only one driver should be enabled at any time. The F81485 features extremely fast switching speeds. Minimal driver propagation delays permit transmission at data rates up to 5 Mbps while low skew minimizes EMI interference. All inputs and outputs contain protection against ESD; all driver outputs feature high source and sink current capability. An epitaxial layer is used to guard against latch-up.

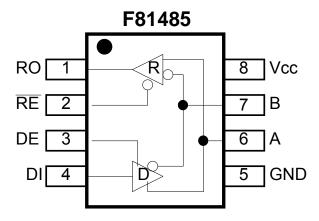
#### 2 Feature List

- Single 5V Supply
- Meets EIA RS-485 standard
- High speed, low power BiCMOS
- -7V to 12V Bus Common-Mode Range Permits
- ±7V Ground Difference Between Devices on the Bus
- ESD ±8KV Contact
- Thermal Shutdown Protection
- Driver Maintains High Impedance in Three-State or with the Power Off
- 70mV Typical Input Hysteresis
- Driver propagation delay: 10 ns typical
- Receiver propagation delay: 15 ns typical
- High-Z outputs with power off
- Pin Compatible with the ADM485, SP485
- 8 Pin SOP Packaging





# 3 Pin Configuration



# 4 Pin Description

IN <sub>t</sub>	- TTL level input pin. - Output pin with 4mA driver.
O <sub>4</sub>	_ ` `
	- Power.

#### 4.1. Power Pin

Pin	Pin Name	Type	Description
5	GND	Р	GND.
8	VCC	Р	4.75V< VCC < 5.25V power supply voltage input.

#### 4.2. Transceiver

Pin	Pin Name	Type	Description
1	RO	O <sub>4</sub>	Receiver Output. When enabled (RE# is low), then if A > B by 200 mV, RO is high. A < B by 200 mV, RO is low.
2	RE#	IN <sub>t</sub>	Active Low Receiver Output Enable pin. A low level enables the receiver output, RO. A high level places it in a high impedance state.
3	DE	IN <sub>t</sub>	Active High Driver Output Enable. A high level enables the driver differential outputs, A and B. The chip will function as a line driver. A low level places it in a high impedance state. The chip will function as a line receiver.



4	DI	IN <sub>t</sub>	Driver Input. When the driver is enabled (DE is high), a logic low on DI forces A low and B high, while a logic high on DI forces A high and B low.
6	Α	I/O	Non-inverting Receiver Input A/Driver Output A.
7	В	I/O	Inverting Receiver Input B/Driver Output B.

Transmitting

Inputs			Line	Outputs		
RE#	DE	DI	Conditio n	В	Α	
Χ	1	1	No Fault	0	1	
Χ	1	0	No Fault	1	0	
X	0	X	Х	Z	Z	
Χ	1	Χ	Fault	Z	Z	

Receiving

	Ouptuts		
RE#	DE	A-B	R
0	0	≥0.2V	1
0	0	≤0.2V	0
0	0	Inputs Open	1
1	0	X	Z





## 5 Electrical Characteristics Request

5.1 Absolute Maximum Ratings

7 / Doordto Maximum Ratingo							
PAR	RAMETER	RATING	UNIT				
	Vcc	±12	V				
	Logic	-0.3 to Vcc +0.5	V				
Input Voltage	Drivers	-0.3 to Vcc +0.5	V				
	Receivers	±15					
	Logic	-0.3 to Vcc +0.5	V				
Output Voltage	Drivers	±15	V				
	Receivers	-0.3 to Vcc +0.5					
Storage Tempreature		-65 to +150	°C				
Lead Temperature (soldering, 10s)		+300	°C				
Powe	r Disspation	500	mW				

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device

#### Test condition: VCC = 5V

PARAMETER	SYMBOL	MIN.	TYP.	MAX	UNIT	CONDITIONS
Supply Voltage		4.75		5.25	V	
Supply Current			900		$\mu$ A	No Load
Operating Temperature		0		70	· C	

#### 5.2 Driver Section

Test condition: VCC = 5V

PARAMETER	SYMBOL	MIN.	TYP.	MAX	UNIT	CONDITIONS		
DC Characteristics								
		GND		Vcc	V	Unloaded, R= ∞		
Differential Output Voltage		2		Vcc	V	With load, R = $50\Omega$ (RS422)		
		1.5		Vcc	V	With load, R = $27\Omega$ (RS485)		
Differential Output Voltage for Complimentary States				0.2	V	$R = 27\Omega$ or $R = 50\Omega$		
Output Voltage				3	V	$R = 27\Omega$ or $R = 50\Omega$		
Input High Voltage		2.0			V	Applies to DE, DI, RE#		
Input Low Voltage				0.8	V	Applies to DE, DI, RE#		
Input Current				±10	$\mu A$	Applies to DE, DI, RE#		
Driver Short Current		35		250	mA	VOUT = High, -7V ≤ Vo ≤ +12V		
		35		250	mA	VOUT = Low, -7V ≤ Vo ≤ +12V		





PARAMETER	SYMBOL	MIN.	TYP.	MAX	UNIT	CONDITIONS		
AC Characteristics								
Maximum Data Rate		5			Mbps	RE# = 5V, DE = 5V		
Driver Input to Output		20	30	60	ns	$t_{PLH}$ ; $R_{DIFF} = 54\Omega$ , $C_{L1} = C_{L2} = 100pF$		
Driver input to Output		20	30	60	ns	$t_{PHL}$ ; $R_{DIFF} = 54\Omega$ , $C_{L1} = C_{L2} = 100pF$		
Driver Skew			5	10	ns	$t_{SKEW} =  t_{DPLH} - t_{DPHL} $		
Driver Rise or Fall Time		3	15	40	ns	10% to 90%, $R_{DIFF}$ = 54 $\Omega$ , $C_{L1}$ = $C_{L2}$ = 100pF		
Driver Enable to Output High			40	70	ns	C <sub>L1</sub> = 100pF		
Driver Enable to Output Low			40	70	ns	C <sub>L1</sub> = 100pF		
Driver Disable Time from Low			40	70	ns	C <sub>L1</sub> = 15pF		
Driver Disable Time from High			40	70	ns	C <sub>L1</sub> = 15pF		

# 5.3 Receiver Section Test condition: VCC = 5V

PARAMETER	SYMBOL	MIN.	TYP.	MAX	UNIT	CONDITIONS
DC Characteristics						
Differential Input Threshold		-300		+0	mV	$-7V \le V_{CM} \le +12V$
Input Hysteresis			10		mV	V <sub>CM</sub> = 0V
Output Voltage High		3.5			V	$I_o = -4mA, V_{ID} = +200mV$
Output Voltage Low				0.4	V	$I_o = +4mA, V_{ID} = -$ 200mV
Output Current				±1	$\mu$ A	0.4V ≤ Vo ≤ 2.4V, RE# = -5V
Input Resistance		12	15		k	$-7V \le V_{CM} \le +12V$
Input Current (A,B), V <sub>IN</sub> = 12V				+1.0	mA	DE = 0V, $V_{cc}$ = 0V or 5.25V, $V_{IN}$ = 12V
Input Current (A,B), V <sub>IN</sub> = -				-0.8	mA	DE = 0V, V <sub>cc</sub> = 0V or 5.25V, V <sub>IN</sub> = -7V
Short Circuit Current		7		95Ω	mA	$0V \le V_{CM} \le V_{cc}$





PARAMETER	SYMBOL	MIN.	TYP.	MAX	UNIT	CONDITIONS
AC Characteristics						
Maximum Data Rate		5			Mbps	RE# = 0V, DE = 0V
Receiver Input to Output		60	90	200	ns	$t_{PLH}$ ; $R_{DIFF} = 54\Omega$ , $C_{L1} = C_{L2} = 100pF$
		60	90	200	ns	$t_{PHL}$ ; $R_{DIFF} = 54\Omega$ , $C_{L1} = C_{L2} = 100pF$
Receiver Skew			13		ns	$t_{SKEW} =  t_{DPLH} - t_{DPHL} $
Receiver Enable to Output Low			20	50	ns	C <sub>RL</sub> = 15pF
Receiver Enable to Output High			20	50	ns	C <sub>RL</sub> = 15pF
Receiver Disable Time from Low			20	50	ns	C <sub>RL</sub> = 15pF
Receiver Disable Time from High			20	50	ns	C <sub>RL</sub> = 15pF

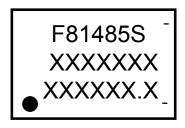


## **Ordering Information**

Part Number	Package Type	Production Flow
F81485S	8-SOP Green Package	Commercial, 0°C to +70°C

### **Top Marking Specification**

The version identification is shown as the bold red characters. Please refer to below for detail:



1st Line: Fintek Logo

 $2^{nd}$  Line: Device Name  $\rightarrow$  **F81485S**, where S means 8-SOP package

2<sup>nd</sup> Line: Assembly Plant Code (X) + Assembled Year Code (X) + Week Code (XX) + Fintek Internal Code (XX) + IC Version (X) where A means version A, B means version B, ...

3<sup>rd</sup> Line: Wafer Fab Code (XXXX...XX)

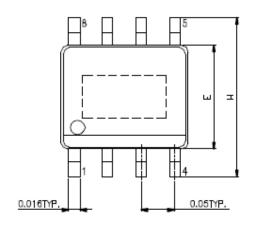
: Pin 1 Identifier

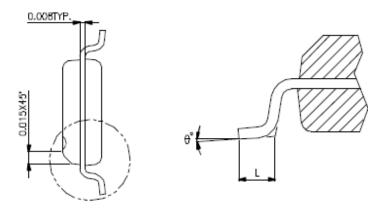


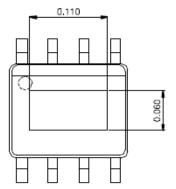


### 8 Package Spec.

#### 8-SOP Package







SEATING PLANE

E.P. VERSION ONLY

SYMBOLS	MIN.	MAX.
Α	0.053	0.069
A1	0.004	0.010
D	0.189	0.196
E	0.150	0.157
Н	0.228	0.244
L	0.016	0.050
e°	0	8

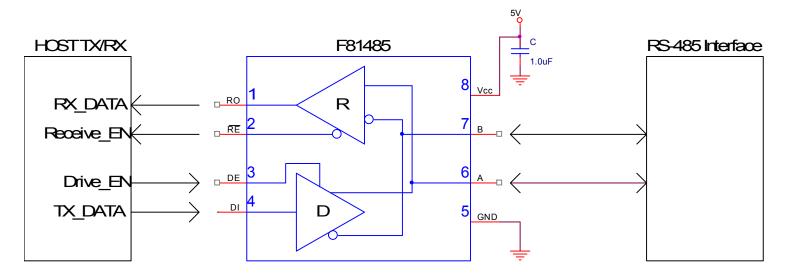
UNIT: INCH

#### NOTES:

- 1.JEDEC OUTLINE : MS-012 AA / E.P. VERSION : N/A
- 2.D MENSIONS "D" DOES NOT INCLUDE WOLD FLASH, PROTRUSIONS OR GATE BURRS, WOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .15mm (.006in) PER SIDE.
- 3.D MENSIONS "E" DOES NOT INCLUDE INTER-LEAD FLASH, OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .25mm (.010in) PER SIDE.



# 9 Application Circuit



#### MODE SELECTION

/RE	Œ	MODE
0	0	RS485 Recieve
1	1	RS485 Drive
0	1	RS485 LoopBack
1	0	Dis R\$485

